Product End-of-Life Disassembly Instructions

Product Category: Desktops
Marketing Name / Model [List multiple models if applicable.]
HP EliteDesk 8 Tower G1i Desktop AI PC; HP EliteDesk 8 Tower G1i E Desktop AI PC/HSC-F007MT

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact HP's Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment.

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	☒ Main board (MB) PCB ☒ Solid state drive (SSD) PCB ☐ Wireless WAN module (WWAN) PCB ☐ Touch module PCB ☒ Power supply PCB ☒ External Keyboard (KB) ☒ External Mouse ☒ Others: Memory PCB	6
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	☒ RTC/CMOS battery ☐ Others: _____	1
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: ☐ screws ☐ snaps ☐ adhesive ☐ other. Explain _____	0
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries		0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	☐ Panel LCD	0

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Cathode Ray Tubes (CRT)		0
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Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	☒ Power Supply capacitor(s) or condenser(s)	1
External electrical cables and cords	☒ AC power cord ☐ Audio, video or data cables ☐ Other: _____	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Hexagon Screwdriver	T15
Crisscross Screwdriver	PH1

3.0 Product Disassembly Process

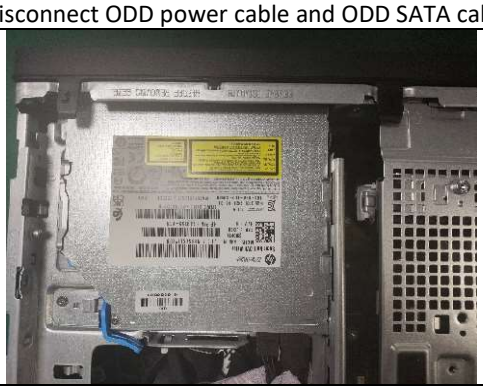
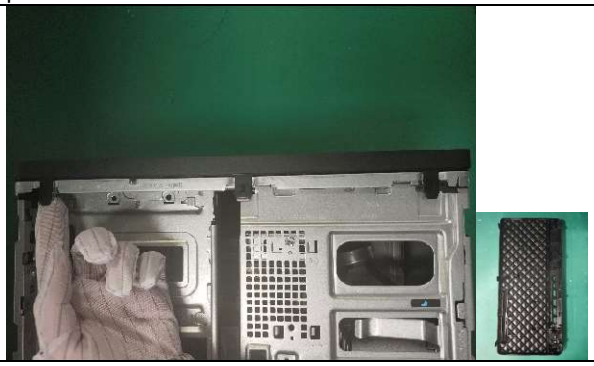
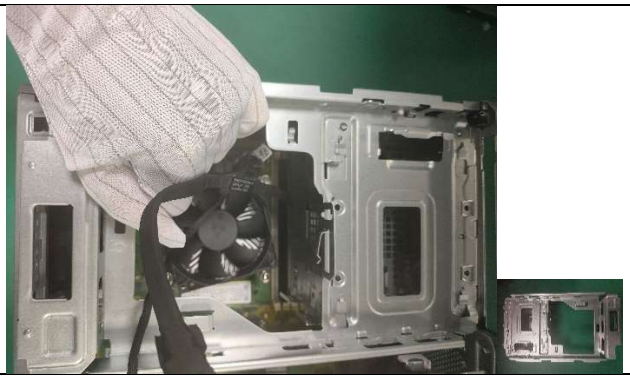
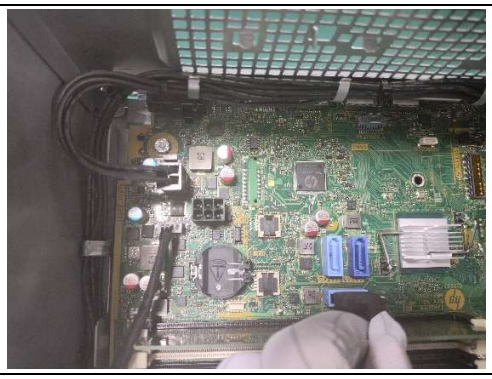
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

1. Loosen the screws on the side cover of the chassis.

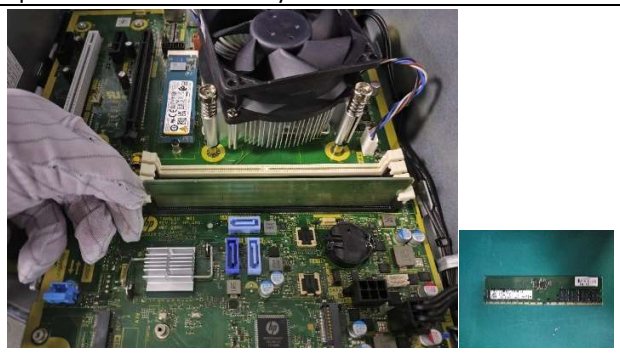
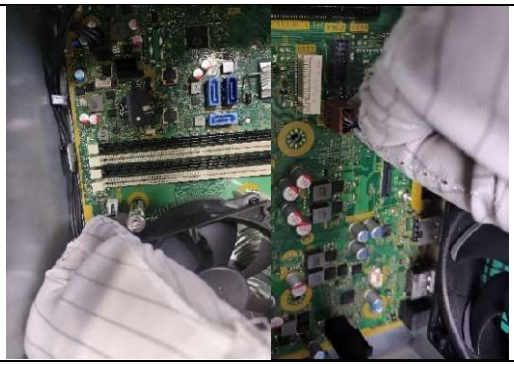
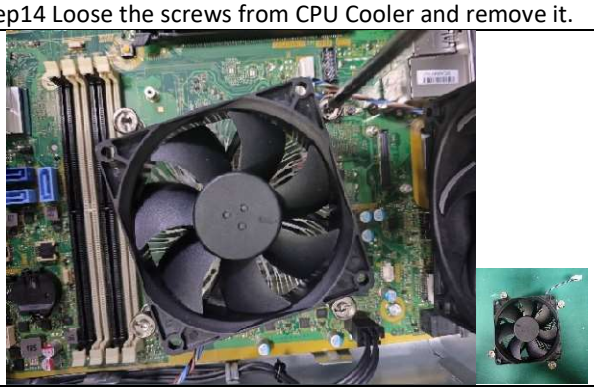
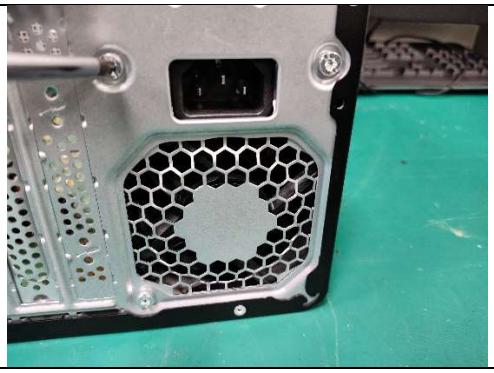
2. Remove the cover from chassis.
3. Disconnect ODD power cable and ODD SATA cable.
4. Press the ODD's latch on ODD cage.
5. Remove the ODD from ODD cage.
6. Remove to the Front Bezel from chassis.
7. Remove the driver cage from Chassis.
8. Disconnect the ODD power cable and ODD SATA cable from the motherboard.
9. Press the side to remove the drive mounting frame from the chassis.
10. Loose the Screw and remove the Front IO Cover.
11. Remove the Memory from the Motherboard.
12. Loose the Screws from SSD and remove it.
13. Disconnect Cooler Fan cable from MB.
14. Loose the screws from CPU Cooler and remove it.
15. Loosen the screws of FAN and remove it.
16. Loose the Screws and remove PSU.
17. Remove the PSU Power connector from the Motherboard.
18. Press the holder and remove the PSU from the chassis.
19. Remove the speaker power cord from the motherboard.
20. Remove speaker from Chassis.
21. Loose the screws from the Motherboard.
22. Remove the Motherboard from Chassis.
23. Remove the CPU from the Motherboard.
24. Remove the battery casing.
25. Remove the battery from the system board.
26. Cut off the strap that ties the output cable to the casing.
27. Tear off the shell label.
28. Unscrew the lock housing screws with a screwdriver.
29. Remove the upper cover of the casing.
30. Pull out the fan terminal.
31. Unscrew the ground screw with a screwdriver.
32. Use a screwdriver to unscrew the locking AC socket screw.
33. Unscrew the locking PCB screws with a screwdriver.
34. Unscrew the FAN lock screw with a screwdriver.

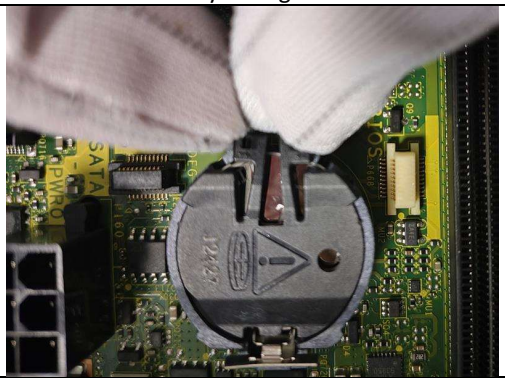
3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: End-of-Life Product Disassembly Instructions (hp.com)

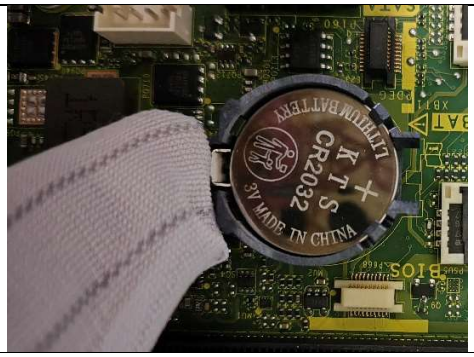
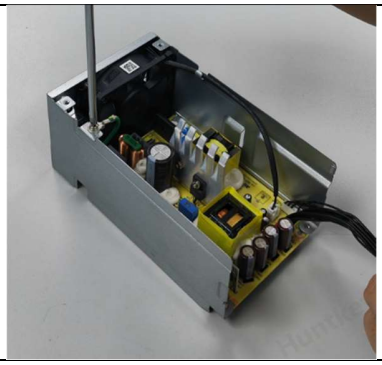
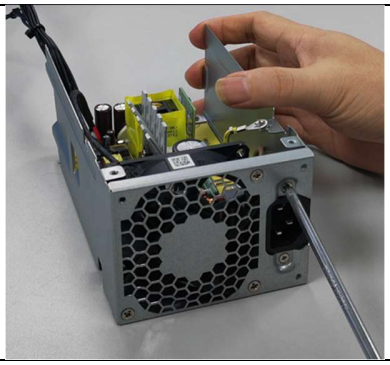
Step1 Loosen the screws on the side cover of the chassis.	Step2 Remove the cover from chassis.

	
Step3 Disconnect ODD power cable and ODD SATA cable.	Step4 Press the ODD's latch on ODD cage.
	
Step5 Remove the ODD from ODD cage.	Step6 Remove to the Front Bezel from chassis.
	
Step7 Remove the driver cage from Chassis.	Step8 Disconnect the ODD power cable and ODD SATA cable from the motherboard.
	

HP Inc. instructions for this template are available at EL-MF877-01

Step9 Press the side to remove the drive mounting frame from the chassis.	Step10 Loose the Screw and remove the Front IO Cover.
	
Step11 Remove the Memory from the Motherboard.	Step12 Loose the Screws from SSD and remove it.
 Memory PCB area surface is greater than 10 sq cm.	 SSD PCA area surface is greater than 10 sq cm.
Step13 Disconnect Cooler Fan cable from MB.	Step14 Loose the screws from CPU Cooler and remove it.
	
Step 15 Loosen the screws of FAN and remove it.	Step16 Loose the Screws and remove PSU.
	

Step17 Remove the PSU Power connector from the Motherboard.	Step18 Press the holder and remove the PSU from the chassis.
	
Step19 Remove the speaker power cord from the motherboard.	Step20 Remove speaker from Chassis.
	
Step21 Loose the screws from the Motherboard.	Step22 Remove the Motherboard from Chassis.
	 Motherboard PCB area surface is greater than 10 sq cm.
Step23 Remove the CPU from the Motherboard.	Step24 Remove the battery casing.
	

Step25 Remove the battery from the system board.	Step26 Cut off the strap that ties the output cable to the casing.
	
Step27 Tear off the shell label.	Step28 Unscrew the lock housing screws with a screwdriver.
	
Step29 Remove the upper cover of the casing.	Step30 Pull out the fan terminal.
	
Step31 Unscrew the ground screw with a screwdriver.	Step32 Use a screwdriver to unscrew the locking AC socket screw.
	
Step33 Unscrew the locking PCB screws with a screwdriver.	Step34 Unscrew the FAN lock screw with a screwdriver.

